

**N-Channel MOSFET** 

## **General Description**

The WSF4085 is the highest performance trench N-Channel MOSFET with extreme high cell density,which provide excellent RDSON and gate chargefor most of the synchronous buck converterapplications.

The WSF4085 meet the RoHS and GreenProduct requirement 100% EAS guaranteed withfull function reliability approved.

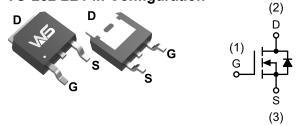
## **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	Ι <sub>D</sub>
40V	6mΩ	85A

#### Applications

- Battery protection
- Load switch
- Uninterruptible power supply

#### **TO-252-2L Pin Configuration**



### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

# Absolute Maximum Ratings (Tc=25 °C, unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	40	V
Vgs	Gate-Source Voltage	V	
I₀@Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	85	A
ID@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	45	A
Ідм	Pulsed Drain Current <sup>2</sup> 120		A
EAS	Single Pulse Avalanche Energy <sup>3</sup> 76		mJ
las	Avalanche Current	39	A
P₀@Tc=25°C	Total Power Dissipation444.6		W
Тѕтс	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range -55 to 150		°C
Reja	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup> 62		°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup> 2.8		°C/W



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## Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Id=250uA	40			V	
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=-1mA		0.034		V/℃	
Rds(on)		Vgs=10V , Id=12A		6.0	7.5	mΩ	
	Static Drain-Source On-Resistance <sup>2</sup>	Vgs=4.5V , Id=10A		9.0	12		
VGS(th)	Gate Threshold Voltage		1.0	1.5	2.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	-Vgs=Vbs , Ib =250uA		4.96		mV/℃	
lass		Vds=32V , Vgs=0V , Tj=25°C			1		
ldss	Drain-Source Leakage Current	Vds=32V , Vgs=0V , Tj=55°C			5	uA	
lgss	Gate-Source Leakage Current	Vgs=±20V , Vds=0V			±100	nA	
gfs	Forward Transconductance	Vos=5V , Io=12A		39		S	
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.6		Ω	
Qg	Total Gate Charge (4.5V)	Vds=20V , Vgs=4.5V , Id=12A		18.8		nC	
Qgs	Gate-Source Charge			4.7			
Qgd	Gate-Drain Charge			8.2			
Td(on)	Turn-On Delay Time			2.6		ns	
Tr	Rise Time	Vdd=15V , Vgs=10V Rg=3.3Ω		14.3			
Td(off)	Turn-Off Delay Time	lo=1A		4.8			
Tf	Fall Time			77			
Ciss	Input Capacitance			2332			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		193		pF	
Crss	Reverse Transfer Capacitance	1		138			
ls	Continuous Source Current <sup>1,5</sup>				60	А	
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			120	А	
Vsd	Diode Forward Voltage <sup>2</sup>	Vgs=0V , Is=1A , Tj=25°C			1	V	

Note :

1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=39A

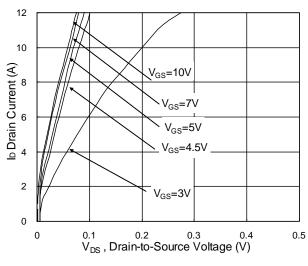
4.The power dissipation is limited by 150 °C junction temperature

5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



#### **N-Channel MOSFET**

## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

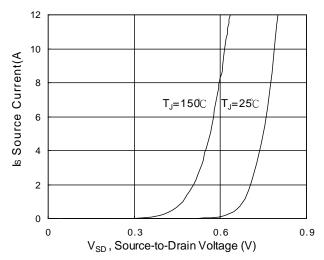
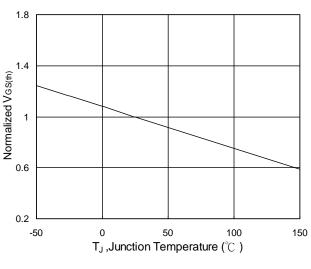
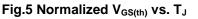


Fig.3 Forward Characteristics of Reverse





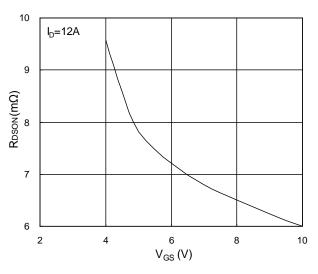


Fig.2 On-Resistance vs. G-S Voltage

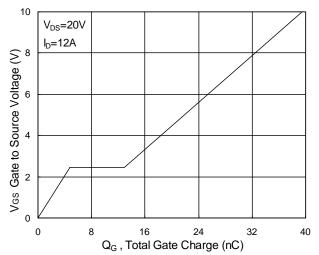
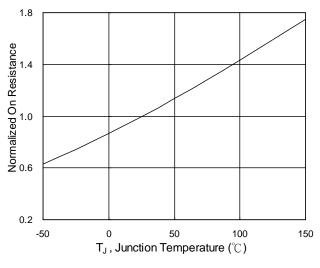


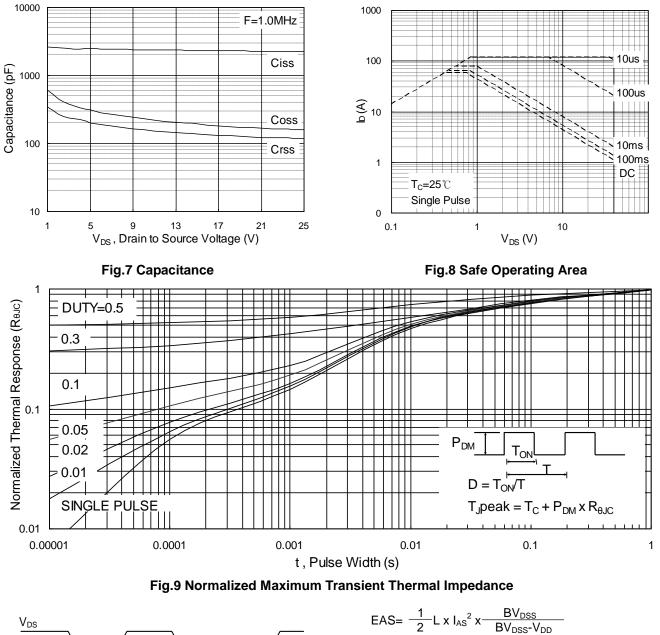
Fig.4 Gate-Charge Characteristics







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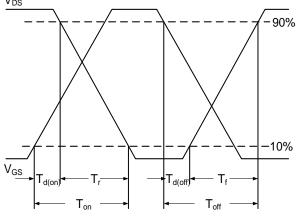


Fig.10 Switching Time Waveform

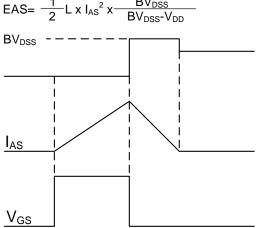
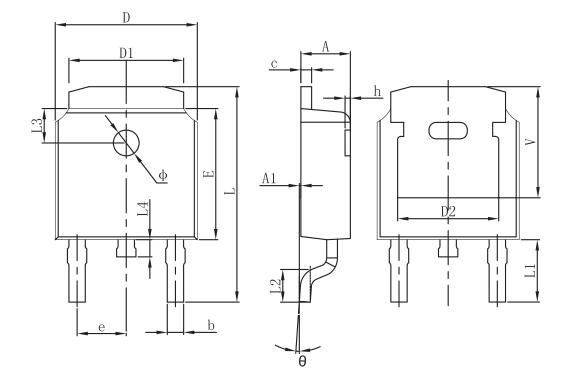


Fig.11 Unclamped Inductive Waveform



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## Packaging information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.635	0.770	0.025	0.030	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 REF.		0.190	).190 REF.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.712	10.312	0.382	0.406	
L1	2.900 REF.		0.114 REF.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 REF.		0.063 REF.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.250	REF.	0.207 REF.		



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